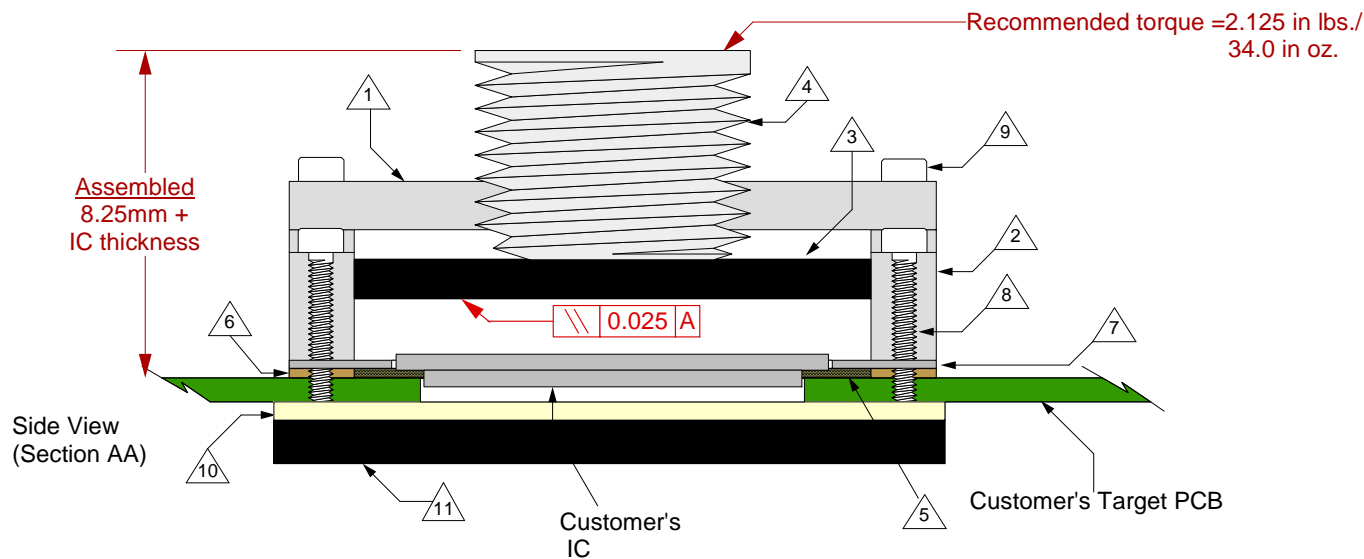
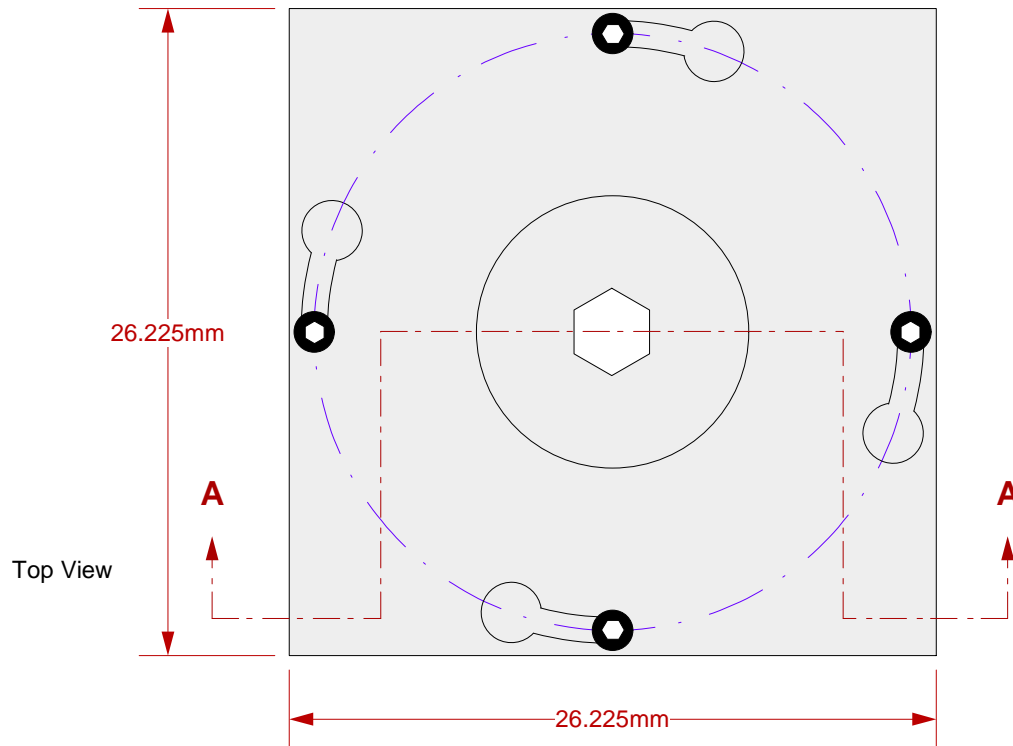



GHz MLF Socket - Direct mount, solderless

Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- IC guide prevents over compression of elastomer
- Easily removable swivel socket lid

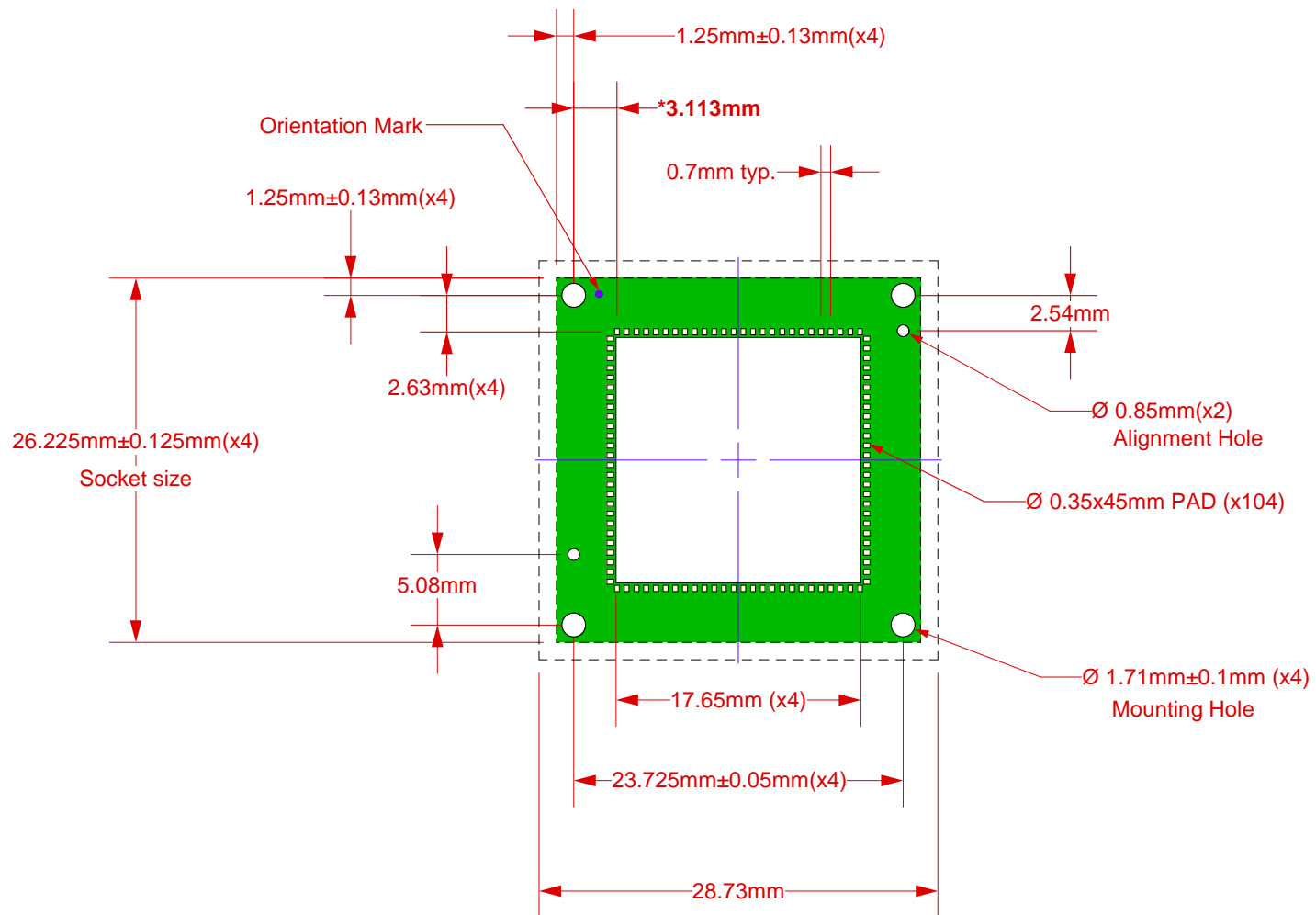


- 1 Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- 2 Socket base: Black anodized Aluminum. Thickness = 5mm.
- 3 Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.
- 4 Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 5mm.
- 5 High temp. Interposer: Thickness = 0.363mm.
- 6 Elastomer Guide: Cirlex Thickness = 0.725mm.
- 7 IC (MLF) Guide: Ultem1000
- 8 Socket base screw: Socket head cap, Alloy steel with black oxide finish, 0-80 fine thread, 9.525mm long.
- 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
- 10 Insulation Plate: FR4/G10, 1.59mm thick.
- 11 Backing Plate: Anodized Aluminum 6.35mm thick.

	XG-QFN-9000 Drawing	Status: Released	Scale: -	Rev: C
	© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Dr. Suite 400 Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: A. Evans	Date: 6/18/08	
		File: XG-QFN-9000 Dwg	Modified: 7/8/09, AE	

All tolerances: $\pm 0.125\text{mm}$ (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout
Top View



Target PCB Recommendations


Total thickness: 1.6mm min.

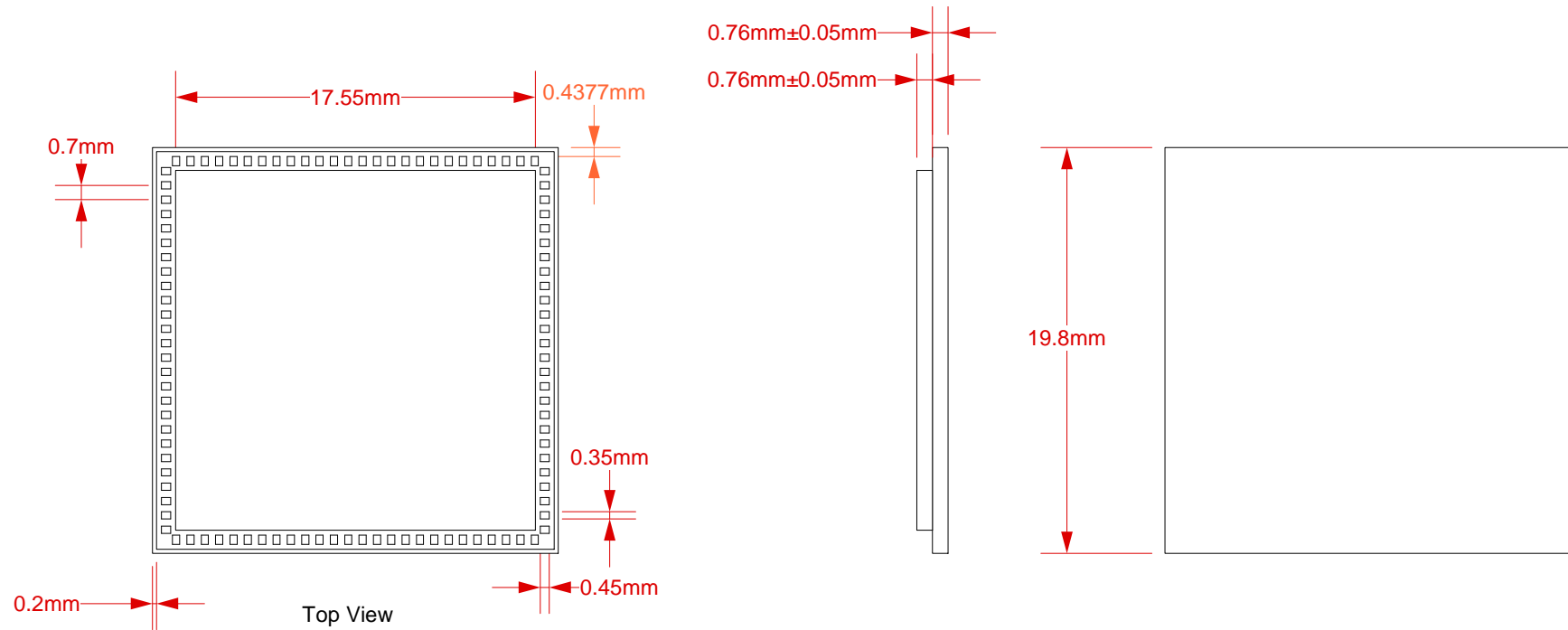
Plating: Gold or Solder finish


PCB Pad height: Same or higher than solder mask

NOTE: Backing plate may be required based on end user's application

Recommended PCB Layout Tolerances:
 $\pm 0.025\text{mm}$ [$\pm 0.001''$] unless stated otherwise.

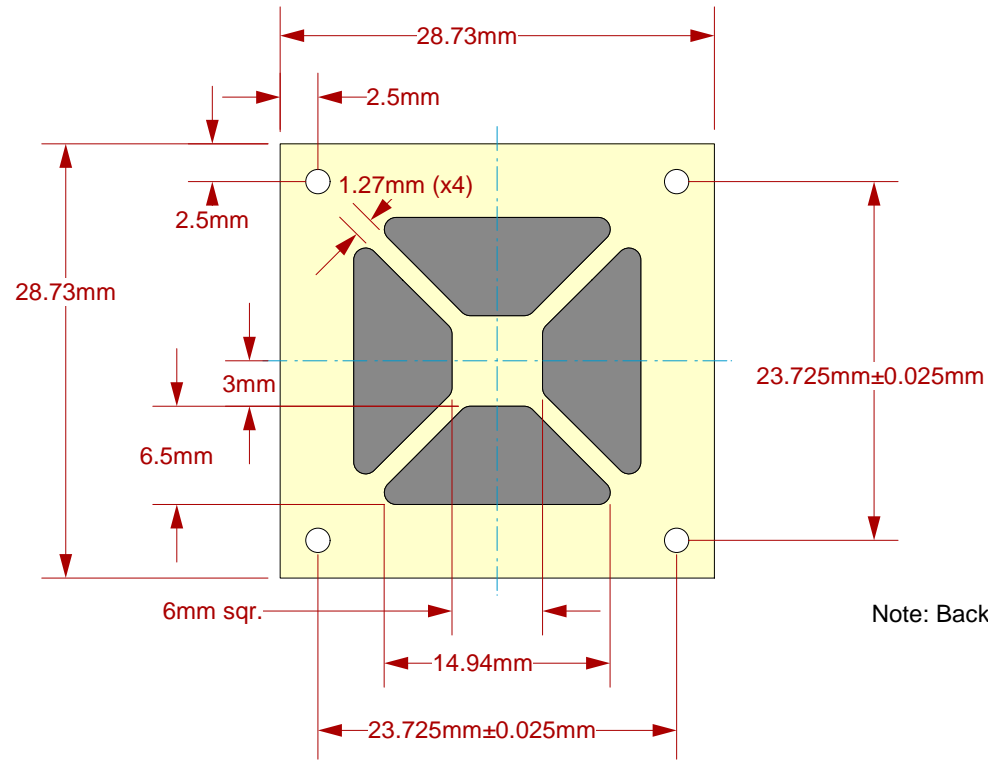
	XG-QFN-9000 Drawing	Status: Released	Scale: -	Rev: C
	© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Dr. Suite 400 Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: A. Evans		Date: 6/18/08
		File: XG-QFN-9000 Dwg	Modified: 7/8/09, AE	



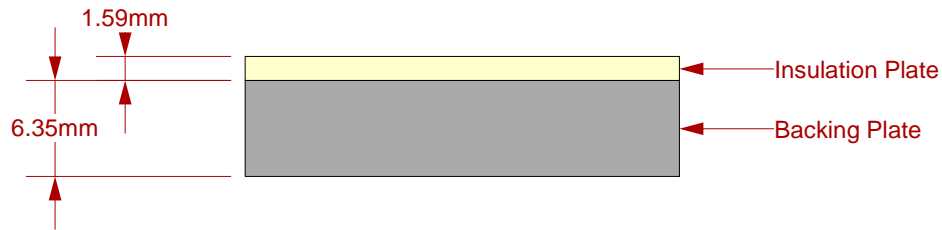
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		Drawing: A. Evans		Date: 6/18/08
		File: XG-QFN-9000 Dwg		Modified: 7/8/09, AE


Backing and insulation Plate

Top View



Side View



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	<p>Drawing: A. Evans</p>	<p>Date: 6/18/08</p>		
	<p>File: XG-QFN-9000 Dwg</p>	<p>Modified: 7/8/09, AE</p>		